

**N-Ch MOSFET** 

# **General Description**

The WSR80N06 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications.

# Features

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

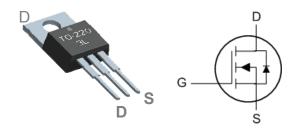
## **Product Summery**

BVDSS	RDSON	ID		
60V	9.1mΩ	80A		

# **Application**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

## **TO-220AB Pin Configuration**



# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	60	V	
$V_{GS}$	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	80	Α	
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	50	Α	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	300	A	
EAS	Single Pulse Avalanche Energy <sup>3</sup> 450		mJ	
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation <sup>4</sup> 110		W	
T <sub>J</sub> T <sub>STG</sub>	Operating Junction Temperature Range	-55 to 175	$^{\circ}$	

## **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit	
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		62	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		0.57	°C/W	



# Electrical Characteristics (T<sub>J</sub>=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0V , $I_D$ =250uA	60			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25℃, I <sub>D</sub> =1mA		0.057		V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =30A		9.1	11.5	
V <sub>GS(th)</sub>	Gate Threshold Voltage	\\ -\\   -250\	2.0	3.0	4.0	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$-V_{GS}=V_{DS}$ , $I_D=250$ uA		-5.68		mV/℃
	Drain-Source Leakage Current	$V_{DS}$ =48V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	uA
I <sub>DSS</sub>		V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20 V$ , $V_{DS}$ = $0 V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =15A	20			S
$Q_g$	Total Gate Charge (4.5V)			36	45	
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =30V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =30A		9.9	18	nC
Q <sub>gd</sub>	Gate-Drain Charge			6.6	15	
T <sub>d(on)</sub>	Turn-On Delay Time	$\begin{array}{c} \color{red} \color{red} \color{blue} \color$		16	28	
Tr	Rise Time			10	21	
$T_{d(off)}$	Turn-Off Delay Time			45	65	ns
T <sub>f</sub>	Fall Time			12	22	]
C <sub>iss</sub>	Input Capacitance			2350		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , f=1MHz		237		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			205		

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			80	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}$ =0V , $I_{S}$ =1A , $T_{J}$ =25 $^{\circ}$ C			1.2	V
t <sub>rr</sub>	Reverse Recovery Time	IF=80A ,dI/dt=100A/μs,TJ=25℃		28		nS
Q <sub>rr</sub>	Reverse Recovery Charge			49		nC

## Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.**  $E_{AS}$  condition : Tj=25  $^{\circ}\!\mathrm{C}$  ,V\_DD=30V,V\_G=10V,L=0.5mH,Rg=25 $\Omega$





## **Typical Characteristics**

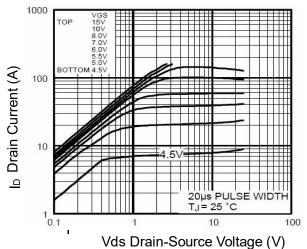


Figure 1 Output Characteristics

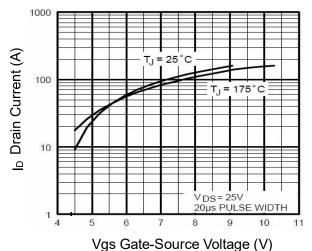


Figure 2 Transfer Characteristics

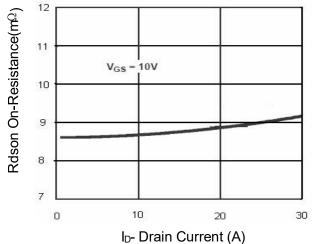


Figure 3 RdsonPrain Current

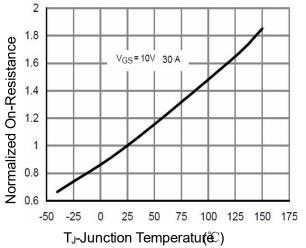
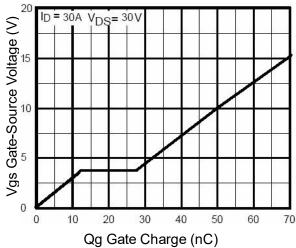


Figure 4 Rdson-JunctionTemperature



**Figure 5 Gate Charge** 

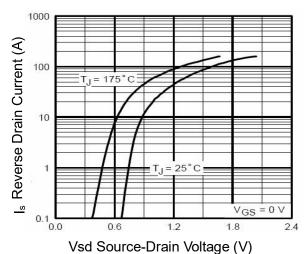


Figure 6 Source- Drain Diode Forward



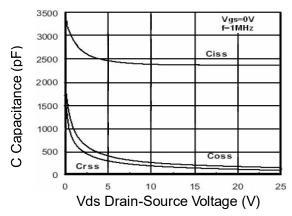


Figure 7 Capacitance vs Vds

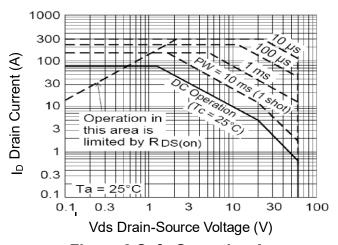


Figure 8 Safe Operation Area

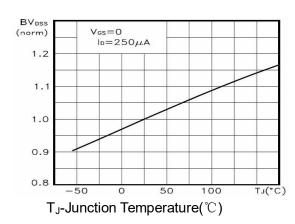


Figure 9 BV<sub>DSS</sub> vs Junction Temperature

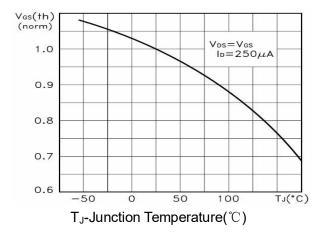


Figure 10 V<sub>GS(th)</sub> vs Junction Temperature

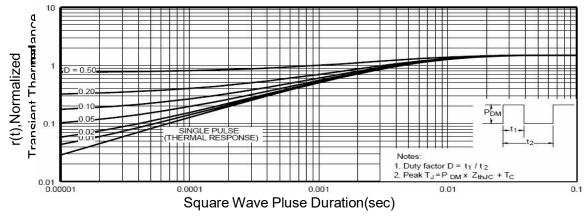


Figure 11 Normalized Maximum Transient Thermal Impedance



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